

TECHNICAL BULLETIN

TG-64 NON-SILICONE THERMAL GREASE

TG-64 is Non-Silicone thermal grease is exceptionally soft, non-silicone thermal grease. In addition to solving the problems of contamination and migration associated with traditional silicone-based thermal grease, this unique material can be spread into an extremely thin film while remaining a homogenous mixture.

This material will not bleed, dry, harden or melt in normal industrial use and provides long-term material stability. It can be used for mounting semiconductor devices, power transistors, and diodes; coupling heat generating assemblies to chassis; heat transfer medium on ballast; thermal joints; and many electronics, automotive and electrical applications.

TYPICAL PROPERTIES:

Color	Grey
Specific Gravity	1.7
Consistency	Smooth Paste
Evaporation, @ 200°C, 24 hrs, %/Wt	0.6
Operating Temperature Range	-55°C to 200°C
Thermal Conductivity, W/m-°K	3.7
Thermal Resistance, °C-in²/W	0.05
Dielectric Strength (0.05" gap), Volts/mil	310
Dielectric Constant, 1 kHz	4.1
Dissipation Factor, 1 kHz	0.003
Volume Resistivity, ohm-cm	1.5×10^{14}

FOR INDUSTRIAL USE ONLY:

These materials are intended for industrial use only, and the practices of good housekeeping, safety and cleanliness should be followed before, during and after use.

WARNING!

Although the system contains low volatility materials, care should be taken in handling. Adequate ventilation of work place and ovens is essential. In case of skin contact, wash thoroughly with soap and water. For eyes, flush immediately with plenty of water for at least 10 minutes and seek medical attention. Refer to Material Safety Data Sheet for additional health and safety information.

SHELF LIFE:

The shelf life of these materials is greater than one year when stored in unopened containers at an average temperature of 25°C.

DISCLAIMER:

All data given here is offered as a guide to the use of these materials and not as a guarantee of their performance. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not to be construed as recommendations to infringe any patent.